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-PLUG ASSY -PCB P/N 10060911 DIM. "A" REF. MATED HEIGHT AFTER REFLOW SEE NOTE 3 -RECPT. ASSY. (SFF TABLE)

END VIEW OF MATED CONNECTORS

DIM. "A"	RECPT. ASSY. P/N
28	55733
18	55701

## NOTES:

(I) MATERIAL:

PRODUCT NUMBER

HOUSING: LCP CONTACT: COPPER ALLOY

PLATING (CONTACT): Au OVER Ni.

UL RATING: 94 V-O

SOLDER BALLS WILL NOT BE PERFECT SHPERICAL SHAPE DUE TO REFLOW ATTACHMENT.

MATED HEIGHT EFFECTED BY CUSTOMERS' PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE & SOLDER PASTÉ.

CONTACTS IN ROWS A, C, E, G, J, K, M, P, R AND T ARE SINGLE BEAM CONTACTS. TYPICALLY USED AS GROUND PINS. (NOTE: CONTACTS IN ROWS J & K ARE TIED TOGETHER [COMMONED])

CONTACTS IN ROWS B.D.F.H.L.N.Q AND S ARE DUAL BEAM CONTACTS. TYPICALLY USED AS SIGNAL PINS.

SPECIFIED POSITIONAL TOLERANCE DEFINES PAD TO PAD LOCATION WITHIN LAND PATTERN. POSITIONAL TOLERANCE OF LAND PATTERN TO FUDICIAL MARKS OR PCB DATUMS SHALL BE DEFINED BY CUSTOMER. FOR RECOMMENDED PRODUCT APPLICATION AND PCB DESIGN DETAILS. SEE DOC. NO. GS-20-016.

NOTES CONTINUED

SPECIFIED POSITIONAL TOLERANCE DEFINES PAD TO PAD LOCATION WITHIN LAND PATTERN. POSITIONAL TOLERANCE OF LAND PATTERN TO FUDICIAL MARKS OR PCB DATUMS SHALL BE DEFINED BY CUSTOMER. FOR RECOMMENDED PRODUCT APPLICATION AND PCB DESIGN DETAILS. SEE DOC. NO. GS-20-016.

(8) FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEADFREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEADFREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FC1 APPLICATION SPECIFICATION.



GIG-Array, PLUG ASSEMBLY 13mm, 296 SIGNAL POSITION catalog no

PDM: Rev:C

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R

С.

REV F - 2006-04-17

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